

## MOS FET MTM981400BBF

## MTM981400BBF Silicon P-channel MOSFET

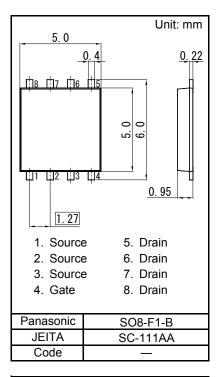
#### For switching

Features

- Low drain-source On-state Resistance RDS(on) typ =  $28 \text{ m}\Omega \text{ (VGS} = -4.5 \text{ V)}$
- Halogen-free / RoHS compliant (EU RoHS / UL-94 V-0 / MSL:Level 1 compliant)

■ Marking Symbol BA

Packaging Embossed type (Thermo-compression sealing) 3 000 pcs / reel (standard)



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#### ■ Absolute Maximum Ratings Ta = 25 °C

Parameter	Symbol	Rating	Unit			
Drain-source Voltage	VDS	-40	V			
Gate-source Voltage	VGS	±20	V			
Drain Current	ID	-7.0	Α			
Drain Current (Pulsed)	IDp	-28	А			
Total Power dissipation <sup>*1</sup>	PD	2	W			
Channel Temperature	Tch	150	°C			
Operating Ambient Temperature	Topr	-40 to +85	°C			
Storage Temperature Range	Tstg	-55 to +150	°C			
Note: *1 Magguring on accomic board at 50 mm x 50 mm x 1.0 mm						

Note: \*1 Measuring on ceramic board at 50 mm  $\times$  50 mm  $\times$  1.0 mm.



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#### ■ Electrical Characteristics Ta = 25°C ± 3°C

Symbol	Conditions	Min	Тур	Max	Unit
VDSS	ID = -1 mA, VGS = 0 V	-40			V
IDSS	VDS = -40 V, VGS = 0 V			-10	μA
IGSS	VGS = ±16 V, VDS = 0 V			±10	μA
Vth	ID = -1.0 mA, VDS = -10.0 V	-1		-2.5	V
RDS(on)1	ID = -7.0 A, VGS = -10 V		19	25	mΩ
RDS(on)2	ID = -3.5 A, VGS = -4.5 V		28	45	
Yfs	ID = -7.0 A, VDS = -10 V	10			S
Ciss			2 700		
Coss	VDS = -10 V, VGS = 0 V, f = 1 MH		190		pF
Crss	]		175		l
td(on)	VDD = -25 V, VGS = 0 V to -10 V		18		
tr	ID = -3.5 A		15		ns
td(off)	VDD = -25 V, VGS = -10 V to 0 V ID = -3.5 A		230		ns
tf			70		
	VDSS IDSS IGSS Vth RDS(on)1 RDS(on)2  Yfs  Ciss Coss Crss td(on) tr td(off)	$ \begin{array}{c c c c c c c c c c c c c c c c c c c $	$ \begin{array}{c c c c c c c c c c c c c c c c c c c $	VDSS ID = -1 mA, VGS = 0 V -40   IDSS VDS = -40 V, VGS = 0 V -40   IGSS VGS = $\pm 16$ V, VDS = 0 V -40   Vth ID = -1.0 mA, VDS = -10.0 V -1   RDS(on)1 ID = -7.0 A, VGS = -10 V 19   RDS(on)2 ID = -3.5 A, VGS = -4.5 V 28    Yfs  ID = -7.0 A, VDS = -10 V 10   Ciss 2700   Coss VDS = -10 V, VGS = 0 V, f = 1 MH; 190   Crss 175   td(on) VDD = -25 V, VGS = 0 V to -10 V 18   tr ID = -3.5 A 15   td(off) VDD = -25 V, VGS = -10 V to 0 V 230	VDSS ID = -1 mA, VGS = 0 V -40   IDSS VDS = -40 V, VGS = 0 V -10   IGSS VGS = $\pm 16$ V, VDS = 0 V $\pm 10$ Vth ID = -1.0 mA, VDS = -10.0 V -1 -2.5   RDS(on)1 ID = -7.0 A, VGS = -10 V 19 25   RDS(on)2 ID = -3.5 A, VGS = -4.5 V 28 45    Yfs  ID = -7.0 A, VDS = -10 V 10 2700   Ciss 2700 2700 2700   Coss VDS = -10 V, VGS = 0 V, f = 1 MH 190 175   td(on) VDD = -25 V, VGS = 0 V to -10 V 18 15   td(off) VDD = -25 V, VGS = -10 V to 0 V 230 230

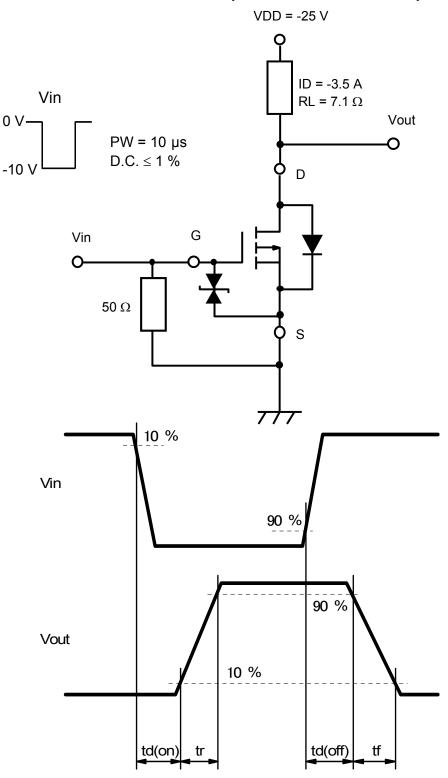
Note: 1. Measuring methods are based on JAPANESE INDUSTRIAL STANDARD JIS C 7030 Measuring methods for transistors. 2. \*1 Pulse test

\*2 Measurement circuit for Turn-on Delay Time/Rise Time/Turn-off Delay Time/Fall Time

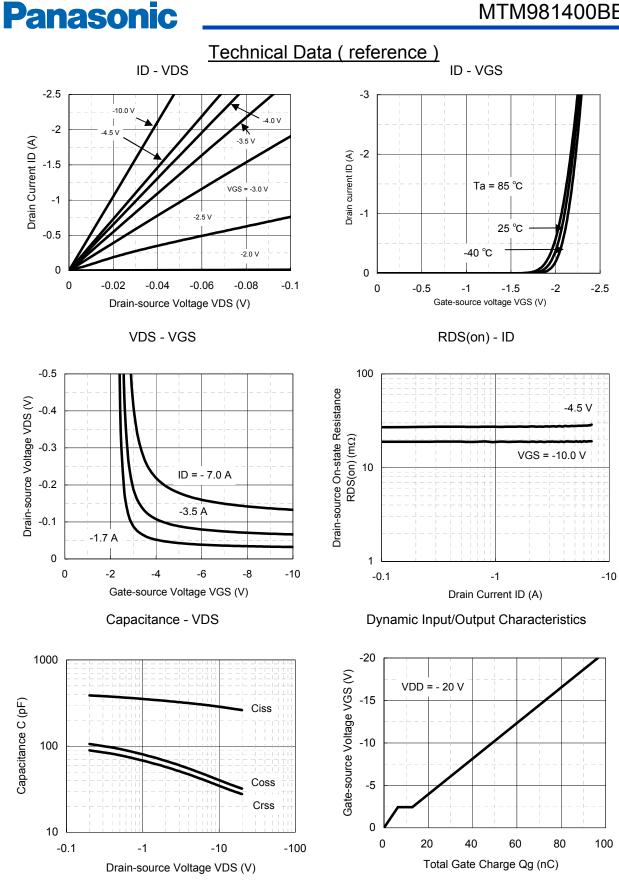
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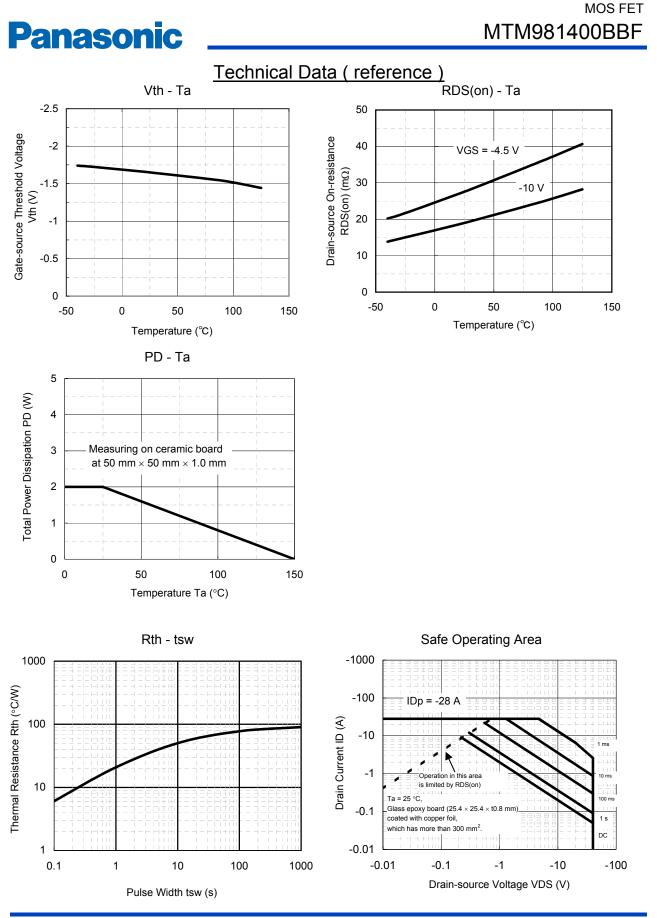
\*2 Measurement circuit for Turn-on Delay Time/Rise Time/Turn-off Delay Time/Fall Time



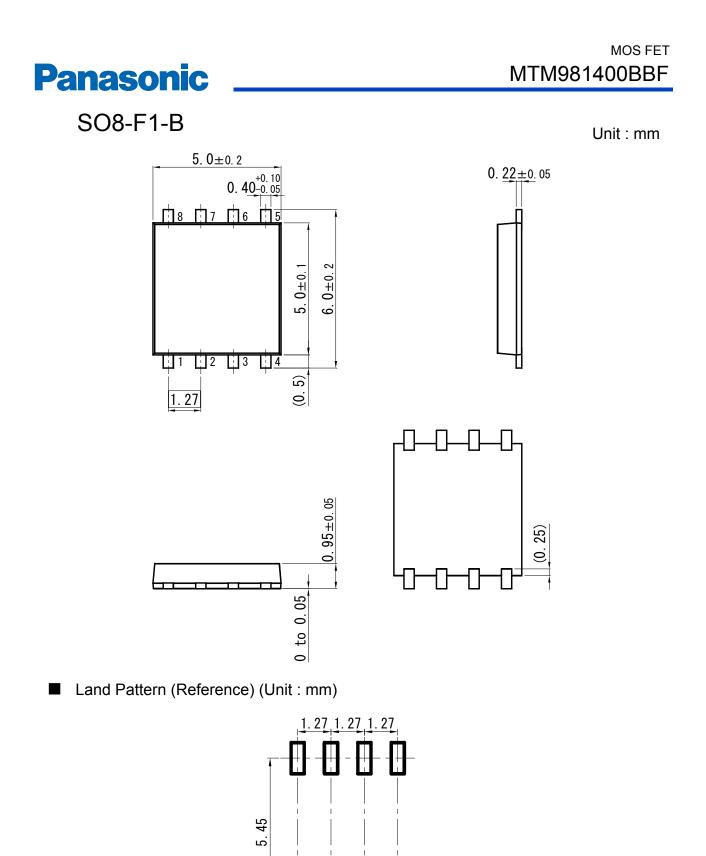
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